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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/971,952	10/04/2001	Casey Prindiville	6047-61248	4096

7590                    03/26/2003

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EXAMINER

CRUZ, LOURDES C

ART UNIT

PAPER NUMBER

2827

# 9

DATE MAILED: 03/26/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Advisory Action</b>	<b>Application No.</b>	<b>Applicant(s)</b>
	09/971,952	PRINDIVILLE ET AL.
	<b>Examiner</b>	<b>Art Unit</b>
	Lourdes C. Cruz	2827

--The MAILING DATE of this communication appears on the cover sheet with the correspondence address--

THE REPLY FILED 28 January 2003 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE. Therefore, further action by the applicant is required to avoid abandonment of this application. A proper reply to a final rejection under 37 CFR 1.113 may only be either: (1) a timely filed amendment which places the application in condition for allowance; (2) a timely filed Notice of Appeal (with appeal fee); or (3) a timely filed Request for Continued Examination (RCE) in compliance with 37 CFR 1.114.

**PERIOD FOR REPLY [check either a) or b)]**

- a)  The period for reply expires 3 months from the mailing date of the final rejection.
- b)  The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection.  
ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).

Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

1.  A Notice of Appeal was filed on \_\_\_\_\_. Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal.
2.  The proposed amendment(s) will not be entered because:
  - (a)  they raise new issues that would require further consideration and/or search (see NOTE below);
  - (b)  they raise the issue of new matter (see Note below);
  - (c)  they are not deemed to place the application in better form for appeal by materially reducing or simplifying the issues for appeal; and/or
  - (d)  they present additional claims without canceling a corresponding number of finally rejected claims.

NOTE: See Continuation Sheet.

3.  Applicant's reply has overcome the following rejection(s): \_\_\_\_\_.
4.  Newly proposed or amended claim(s) \_\_\_\_\_ would be allowable if submitted in a separate, timely filed amendment canceling the non-allowable claim(s).
5.  The a) affidavit, b) exhibit, or c) request for reconsideration has been considered but does NOT place the application in condition for allowance because: \_\_\_\_\_.
6.  The affidavit or exhibit will NOT be considered because it is not directed SOLELY to issues which were newly raised by the Examiner in the final rejection.
7.  For purposes of Appeal, the proposed amendment(s) a) will not be entered or b) will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended.

The status of the claim(s) is (or will be) as follows:

Claim(s) allowed: \_\_\_\_\_.

Claim(s) objected to: \_\_\_\_\_.

Claim(s) rejected: 30-32, 36-40.

Claim(s) withdrawn from consideration: \_\_\_\_\_.

8.  The proposed drawing correction filed on \_\_\_\_\_ is a) approved or b) disapproved by the Examiner.

9.  Note the attached Information Disclosure Statement(s)( PTO-1449) Paper No(s). \_\_\_\_\_.

10.  Other: \_\_\_\_\_.

K. C. CRUZ  
Supervisory Patent Examiner  
2829

Continuation of 2. NOTE: The amendments to the claims include recitation of "defective" in the claim itself, and out of the pre-amble. See that limitations set in the pre-amble are not read in the claims. Therefore, the claims as amended need to be further considered by the examiner.

**In the claims:**

Please amend the claims as follows:

30. (Currently Amended) A defective semiconductor package comprising:

- (a) a defective substrate having a first surface with a pattern of conductors;
- (b) the defective substrate having a second surface including a defective die attach site;
- (c) a wire bond slot forming an opening through the defective substrate extending from the first surface to the second surface; and
- (d) a cover member attached to the defective substrate on the second surface so as to cover at least a portion of the opening, wherein the cover member does not comprise a functional die.

31. (Original) The defective semiconductor package of claim 30, wherein the cover member comprises tape.

32. (Original) The defective semiconductor package of claim 30, wherein the cover member covers a majority of the opening.

36. (Previously added) The defective semiconductor package of claim 30, wherein the cover member covers from about 70% to about 98% of the opening formed by the wire bond slot.

37. (Previously added) The defective semiconductor package of claim 30, wherein the wire bond slot is associated with the defective die attach site.

38. (Previously added) The defective semiconductor package of claim 30, wherein the cover member comprises a defective die.

39. (Previously added) The defective semiconductor package of claim 30, wherein the cover member covers from about 80% to about 90% of the opening formed by the wire bond slot.

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40. (Previously added) The defective semiconductor package of claim 30, wherein the cover member covers at least about 70% of the opening formed by the wire bond slot.